



MATERIALS:
 PLASTIC COMPONENTS: LCP 30% G.F. BLACK (HOUSING)
 PA 4.6 30% G.F. RAL 6034 (EJECTOR PARTS)
 TERMINALS: Ph-Bz CuSn 8 0.20 THICK
 PLATING: CONTACT AREA: 0.76 μm Au MIN OVER 1.27 μm Ni MIN
 SOLDERING AREA: 3.8 μm Sn MIN OVER 1.27 μm Ni MIN
 SOLDER PINS: PhBz CuSn 6 0.20 THICK, TIN PRE-PLATED

- NOTES:
 [1] WIDTH OF THE CARD SLOT
 [2] PACKAGING: SEE DRAWING PK-94351-001
 [3] ALL DIMENSIONS SHALL CONFORM TO MMC SYSTEM SPECIFICATIONS
 [4] PRODUCT CHARACTERISTIC ACCORDING TO: PS-94351-001
 [5] WITH REFERENCE TO THE PLANE (THE SEATING PLANE) GIVEN BY THE LOWEST OF THE SEVEN SOLDER TAILS AND THE TWO FRONT STAND-OFFS, THE OTHER TWO STAND-OFFS, PROVIDED THAT THEIR HEIGHT IS ACCORDING TO THE DRAWING, SHALL NOT CROSS-OVER THE SEATING PLANE
 [6] MEASURED FROM THE REFERENCE PLANE
 [7] DIAMETER OF TINNING AROUND THE PCB HOLE = 1.9 mm, DIAMETER OF SOLDERING PASTE = 2.5 mm
 [8] HEIGHT OF THE CARD SLOT: 1.60 +0.10/-0.05 mm @ THE SIDES OF THE SLOT, 1.60 +0.10/-0.10 @ THE CENTER OF THE SLOT
 [9] PICK & PLACE AREA FREE OF FLASHES, GATE MARKS, FAT
 [10] STRAIGHTNESS OF THE CARD SLOT AXIS

Std Descr. :MMC CONN W/EJECTOR 4 HIGH*

EC NO: Z2010-0111 DRWN: GZUIN 2010/01/22 CHKD: LSANTES 2010/01/20 APPR: FBISELLO 2010/07/05	QUALITY SYMBOLS ▽ - 0 ▽ - 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 2:1	DESIGN UNITS METRIC	FIRST ANGLE PROJECTION	REVISE ON CAD ONLY
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.05 ± --- 1 PLACE ± 0.15 ± ---	DIMENSION STYLE MM ONLY	TITLE MMC CONNECTOR WITH EJECTOR (H=4 MM)			
		ANGULAR ± 2 °	DRAFT WHERE APPLICABLE	MOLEX INCORPORATED			
		MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	MATERIAL NO. 94351-5002	DOCUMENT NO. SD-94351-001	SHEET NO. 1 OF 1	